

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

TLGC256

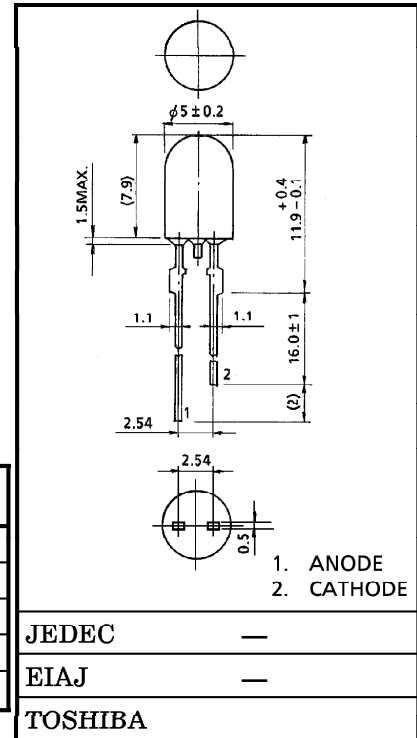
2 CHIP LED LAMP FOR MESSAGE BOARD

Unit in mm

- 2 Chip Series Connection
- All Plastic Mold Type : Clear Transparent Lens
- Low Drive Current, High Intensity Green Light Emission
Recommended Forward Current : $I_F = 15 \sim 20\text{mA}$ (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- Wide Radiation-Suitable for Message Board ($\pm 45\text{deg}$)

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current	I_F	30	mA
Reverse Voltage	V_R	8	V
Power Dissipation	P_D	170	mW
Operating Temperature Range	T_{opr}	$-30 \sim 85$	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	$-40 \sim 100$	$^\circ\text{C}$



Weight : 0.35g

ELECTRO-OPTICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V_F	$I_F = 20\text{mA}$	—	4.3	5.4	V
Reverse Current	I_R	$V_R = 8\text{V}$	—	—	5	μA
Luminous Intensity	I_V	$I_F = 20\text{mA}$	27.2	90	—	md
Peak Emission Wave Length	λ_p	$I_F = 20\text{mA}$	—	567	—	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20\text{mA}$	—	25	—	nm

PRECAUTION

Please be careful of the followings

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : below the Lead Stopper)
- If the lead is formed, the lead should be formed below the Lead Stopper without forming stress to the resin. Soldering should be performed after lead forming.

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